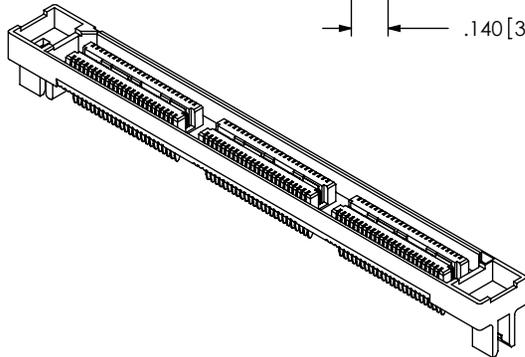
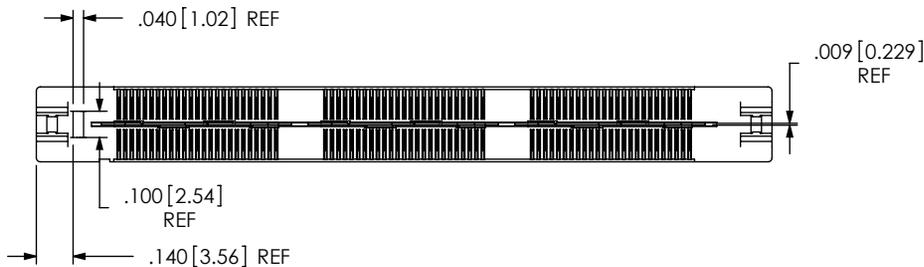
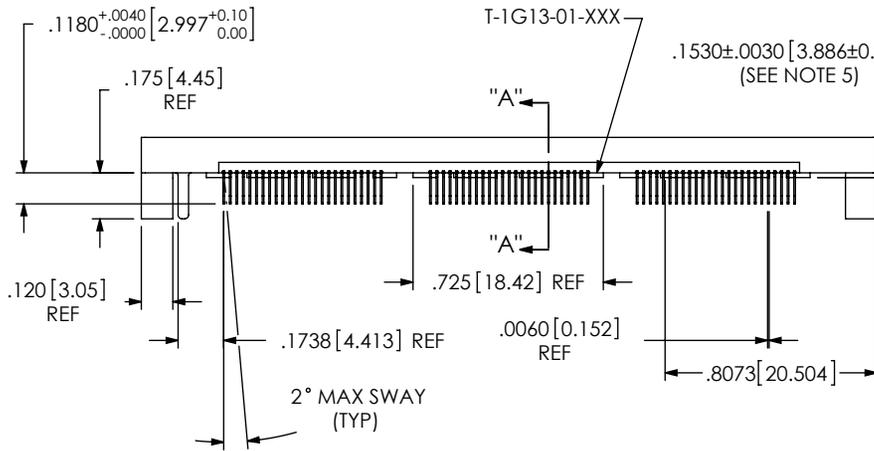
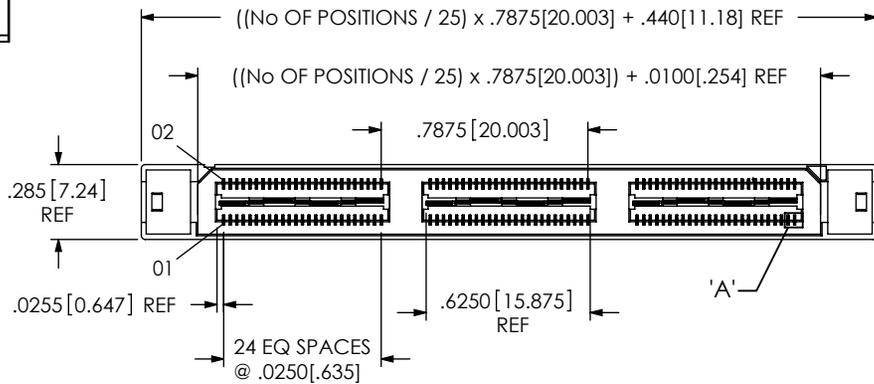


DO NOT SCALE FROM THIS PRINT



QSS-XXX-01-XXX-D-EMX

No OF POSITIONS
 -025, -050, -075,
 *100, *125
 (PER ROW)
 * = SEE NOTE 11 & 12

LEAD STYLE
 -01: $.1530[3.886]$

PLATING SPECIFICATION
 -F: FLASH SELECTIVE GOLD, MATTE TIN TAIL
 (USE C-162-XX-F & T-1G13-01-F)
 -L: LIGHT SELECTIVE GOLD, MATTE TIN TAIL
 (USE C-162-XX-L & T-1G13-01-L)
 -H: HEAVY GOLD
 (USE C-162-XX-H & T-1G13-01-G)
 -STL: SELECTIVE GOLD, TIN/LEAD
 (USE C-162-XX-STL & T-1G13-01-STL)
 -FTL: FLASH SELECTIVE GOLD, TIN/LEAD
 (USE C-162-XX-FTL & T-1G13-01-FTL)

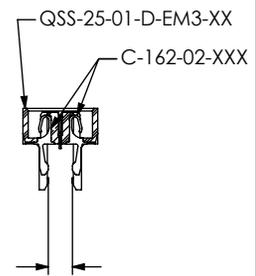
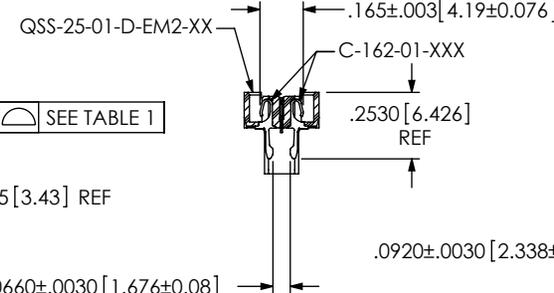
EDGE MOUNT THICKNESS
 -EM2: $.064[1.63] \pm .004$ PCB
 (USE QSS-25-01-D-EM2-XX & C-162-01-X)
 -EM3: (USE QSS-25-01-D-EM3-XX
 & C-162-02-X)

SEE NOTE 10

ROW SPECIFICATION

-D: DOUBLE (USE QSS-25-01-D-EMX-XX)

No OF BANKS



NOTES:

1. (C) REPRESENTS A CRITICAL DIMENSION.
2. CONTACT RETENTION: 6 OZ MIN.
3. GROUND PLANE RETENTION: 8 OZ MIN.
4. PARTS ARE MOLD TO POSITION.
5. MAX VARIANCE OF $.002[.05]$.
6. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING.
7. NOTE DELETED.
8. BOARD THICKNESS TO BE MEASURED FROM SOLDER PAD TO SOLDER PAD.
9. SEE http://www.samtec.com/processing/edgemt_tectalk/index.htm FOR INFORMATION ON PROCESSING EDGE MOUNT PARTS TO BOARDS.
10. -EM3 & IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY. PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP WITH ORDER INQUIRIES.
11. FOR NEW APPLICATIONS REQUIRING THESE POSITIONS, PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP.
12. AVAILABLE FOR EXISTING CUSTOMERS ONLY.

TABLE 1		
No OF POSITIONS	GND PLANE COPLANARITY	ASSEMBLY BOW
-025 THRU -075	$.004[.10]$	$.004[.10]$
*100 THRU *125	$.005[1.27]$	$.005[1.27]$

* = SEE NOTE 11 & 12

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES.
 TOLERANCES ARE:
 DECIMALS ANGLES
 .XX: $\pm .01[.3]$ 2°
 .XXX: $\pm .005[.13]$
 .XXXX: $\pm .0020[.051]$

PROPRIETARY NOTE
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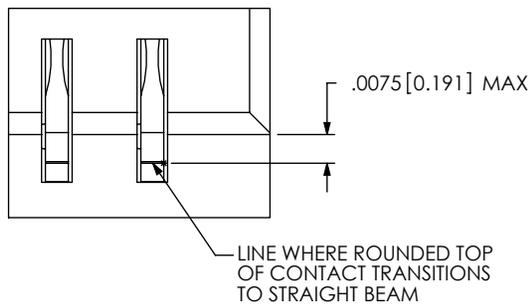
MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 1.375:1
 INSULATOR: LCP, COLOR: BLACK
 CONTACT: PHOS BRONZE
 GROUND PLANE: PHOS BRONZE

samtec
 520 PARK EAST BLVD, NEW ALBANY, IN 47150
 PHONE: 812-944-6733 FAX: 812-948-5047
 e-Mail: info@SAMTEC.com code: 55322

DESCRIPTION: .635mm EDGE MOUNT HS SOCKET ASSEMBLY

DWG. NO. QSS-XXX-01-XXX-D-EMX

BY: DEAN P 5/26/2000 SHEET 1 OF 2



DETAIL 'A'
SCALE 20:1

CRITICAL DIMENSION INSPECTION INSTRUCTION TABLE	
ASSEMBLY OPERATION	IN-PROCESS INSPECTION
FILL C-162-XX-XXX	C1, C2, C3, C4*, C5*, C8
FILL T-1G13-01-XXX	C7
WHERE APPLICABLE *	

<p>PROPRIETARY NOTE THIS DOCUMENT CONTAINS INFORMATION CONFIDENTIAL AND PROPRIETARY TO SAMTEC, INC. AND SHALL NOT BE REPRODUCED OR TRANSFERRED TO OTHER DOCUMENTS OR DISCLOSED TO OTHERS OR USED FOR ANY PURPOSE OTHER THAN THAT WHICH IT WAS OBTAINED WITHOUT THE EXPRESSED WRITTEN CONSENT OF SAMTEC, INC.</p> <p>DO NOT SCALE DRAWING</p> <p>SHEET SCALE: 2:1</p>	 <p>520 PARK EAST BLVD, NEW ALBANY, IN 47150 PHONE: 812-944-6733 FAX: 812-948-5047 e-Mail: info@SAMTEC.com code: 55322</p>	
	DESCRIPTION: .635mm EDGE MOUNT HS SOCKET ASSEMBLY	
	DWG. NO. QSS-XXX-01-XXX-D-EMX	
	BY: DEAN P	5/26/2000